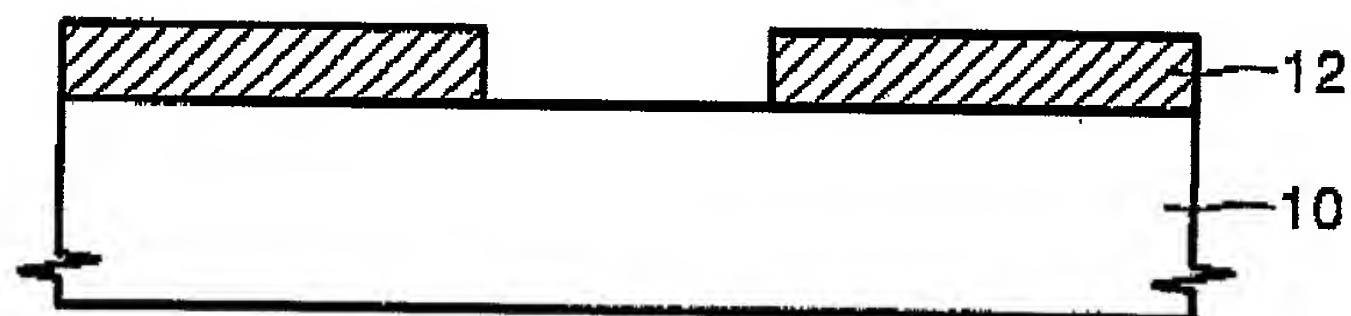
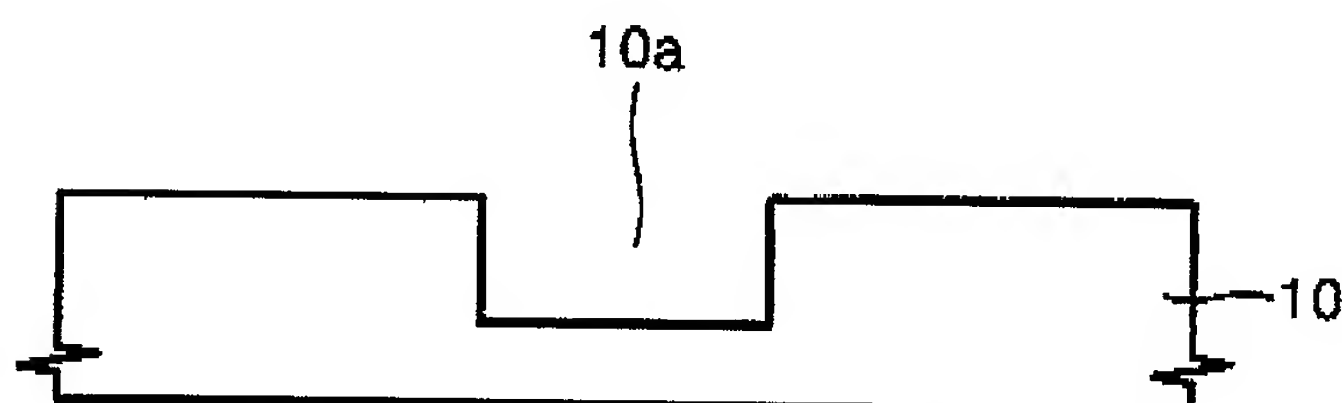


Serial No Not Assigned Docket No 1751-300  
Title Method of Through-Etching Substrate  
Inventor Kyoung-doug Min, et al

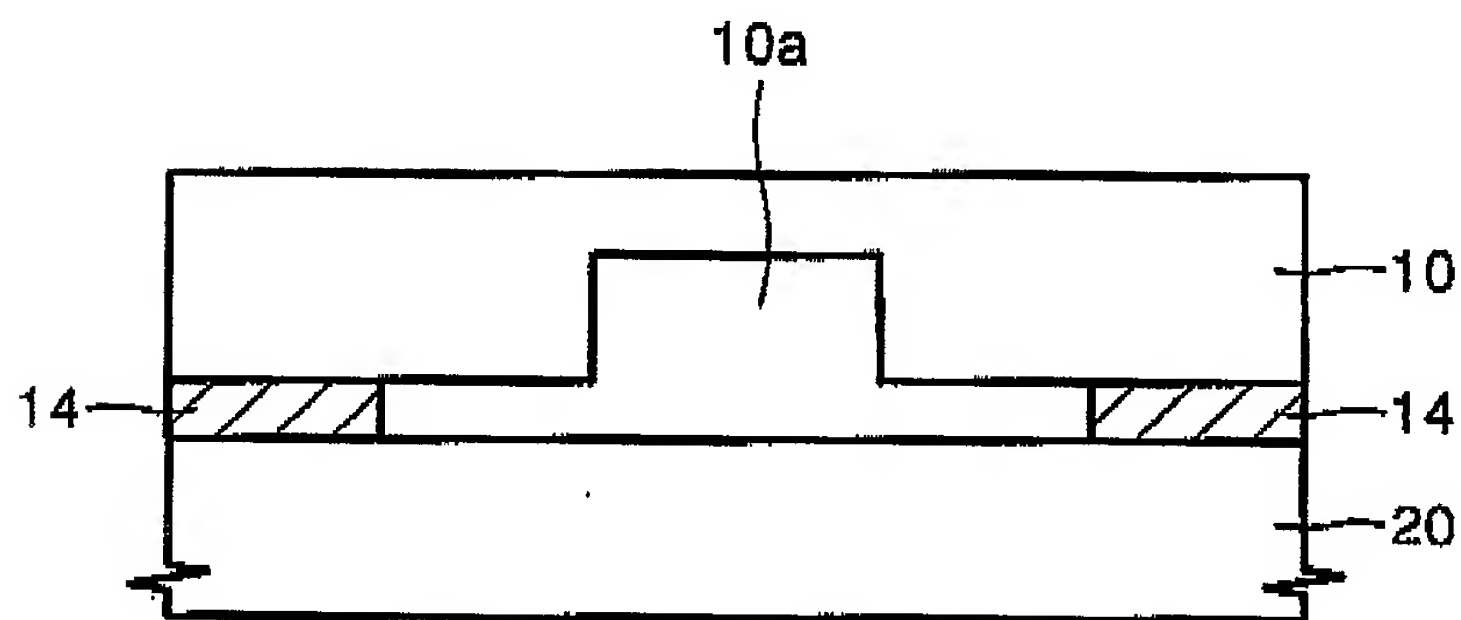
# FIG. 1 (PRIOR ART)



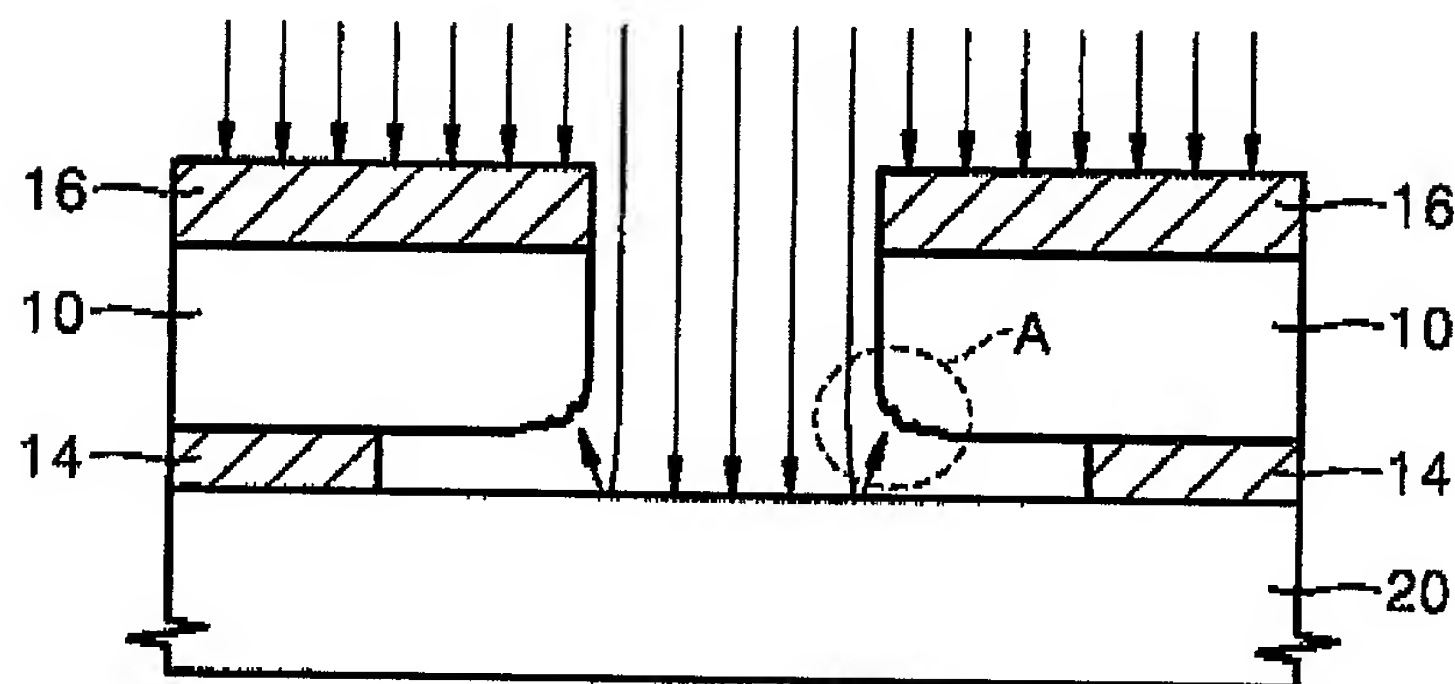
# FIG. 2 (PRIOR ART)



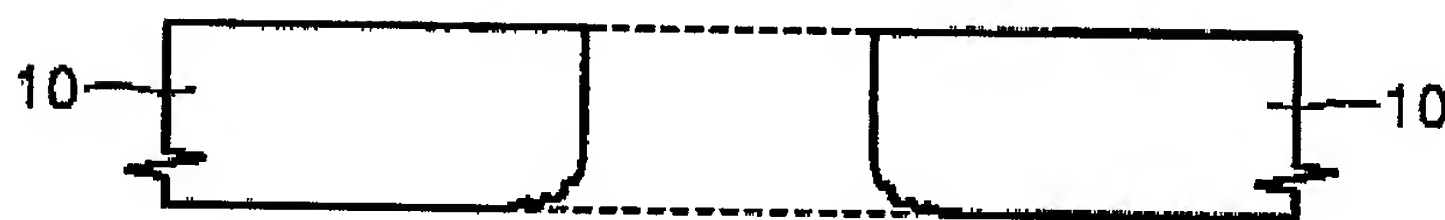
# FIG. 3 (PRIOR ART)



# FIG. 4 (PRIOR ART)



# FIG. 5 (PRIOR ART)



Serial No. Not Assigned Docket No. 1751-300  
 Title: Method of Through-Etching Substrate  
 Inventor: Kyoung-doug Min, et al

FIG. 6

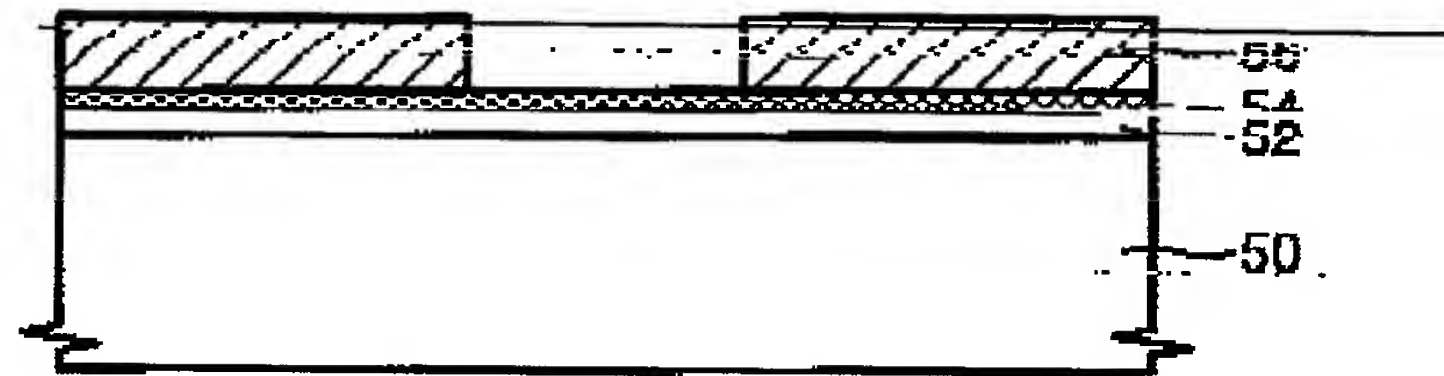


FIG. 7

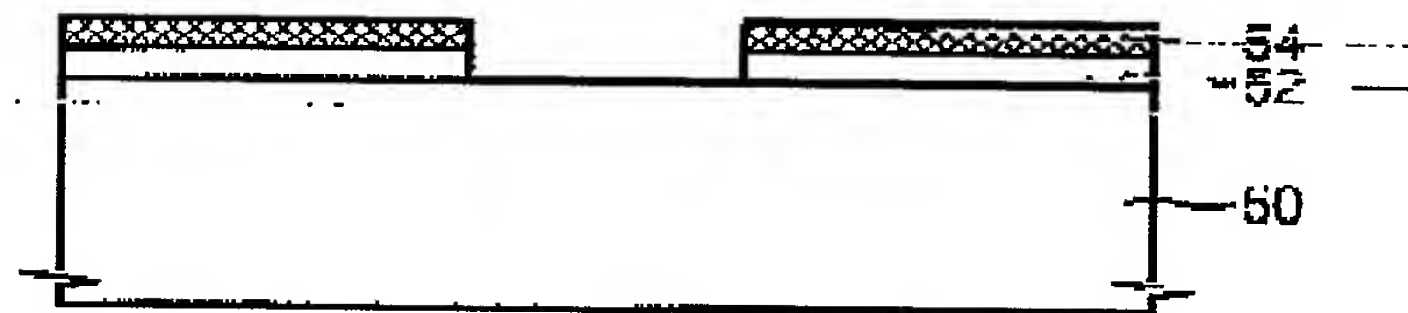
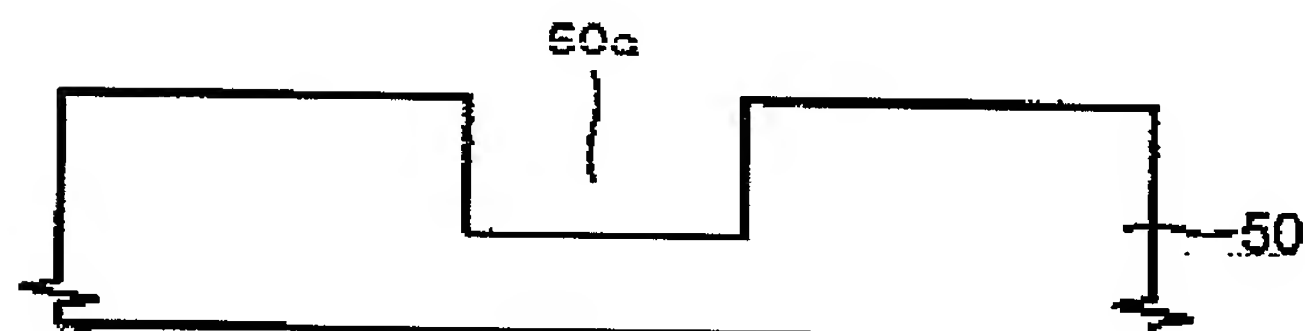
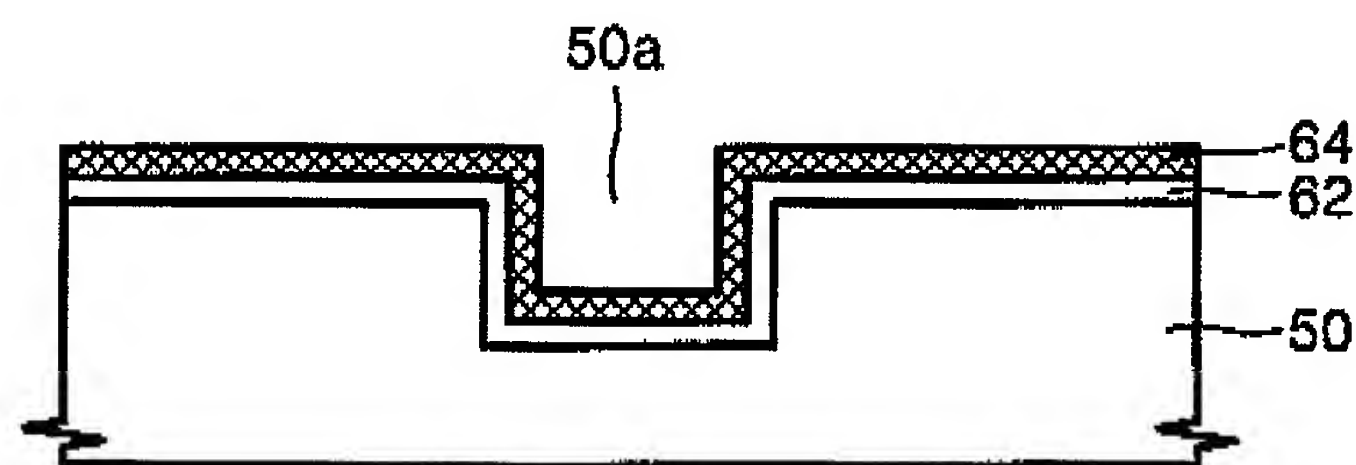
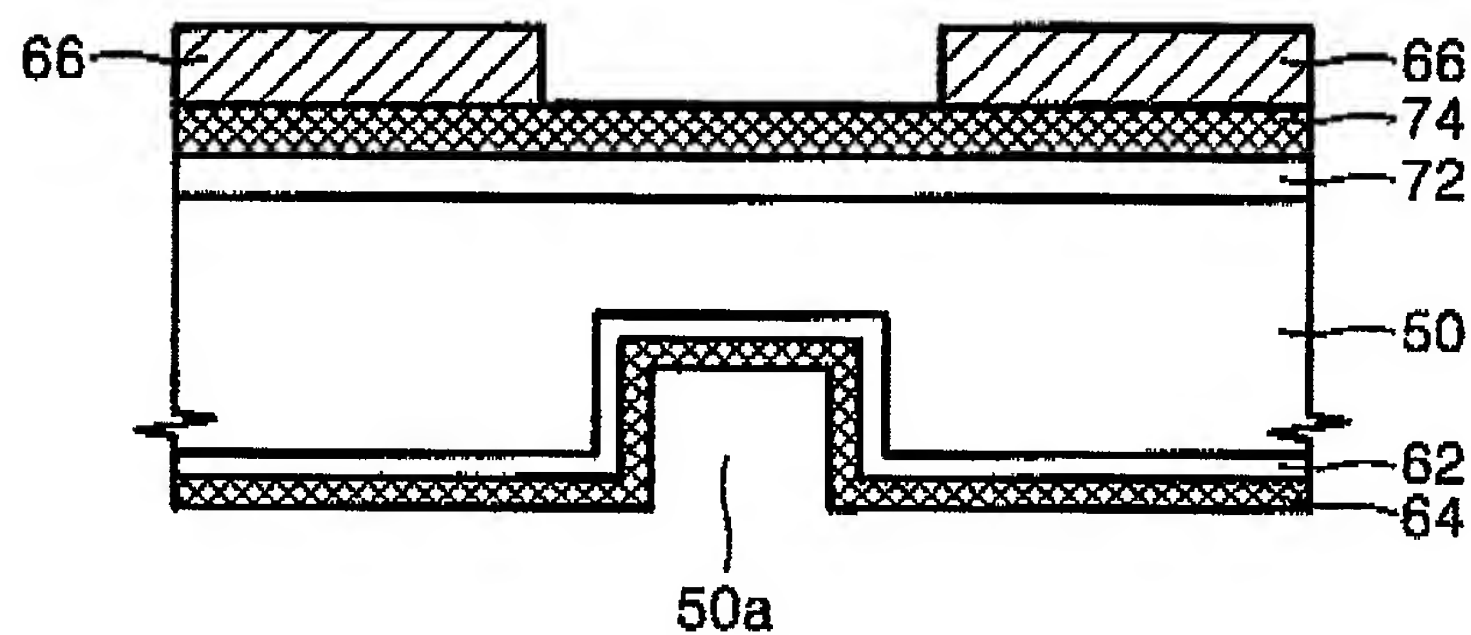
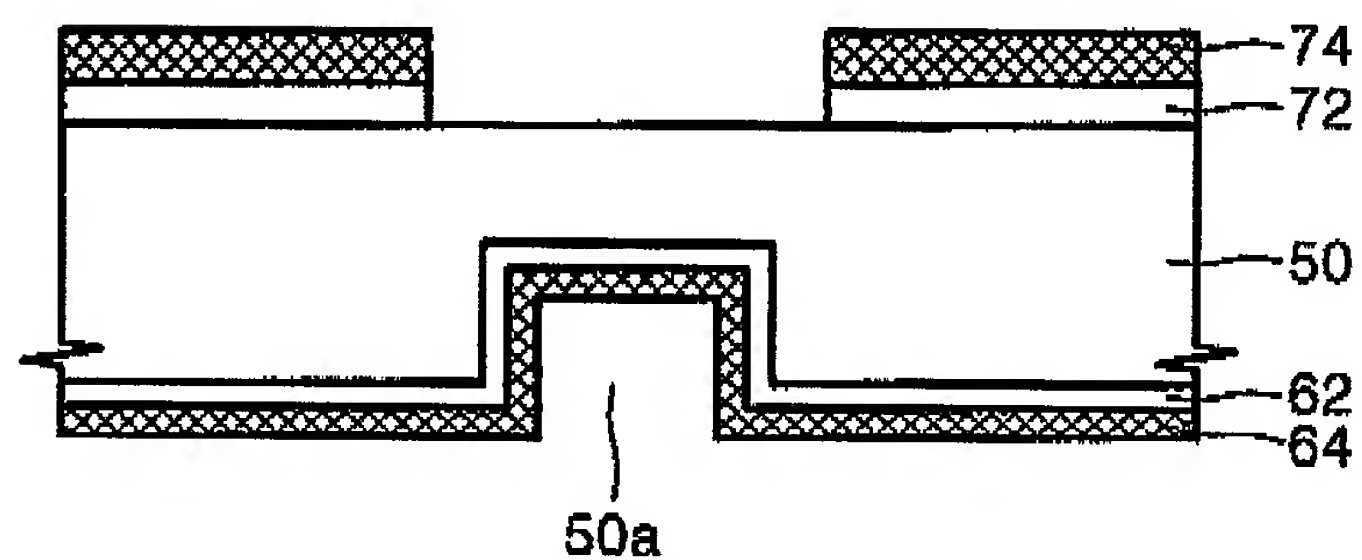


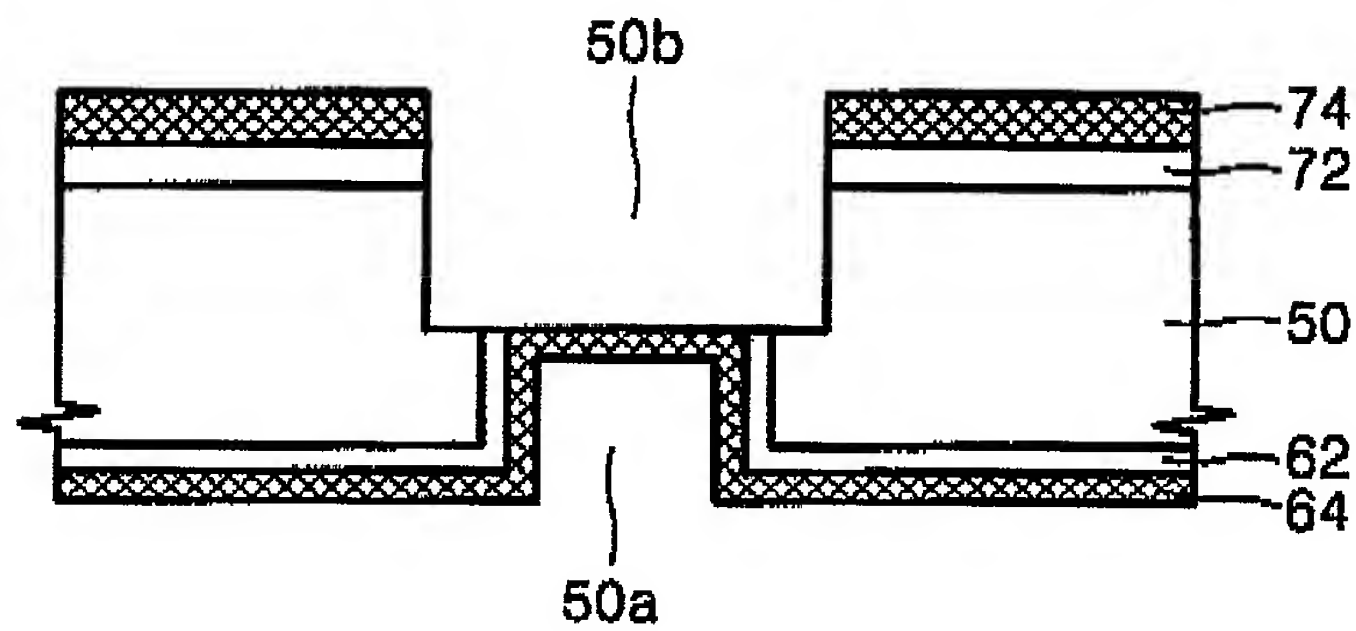
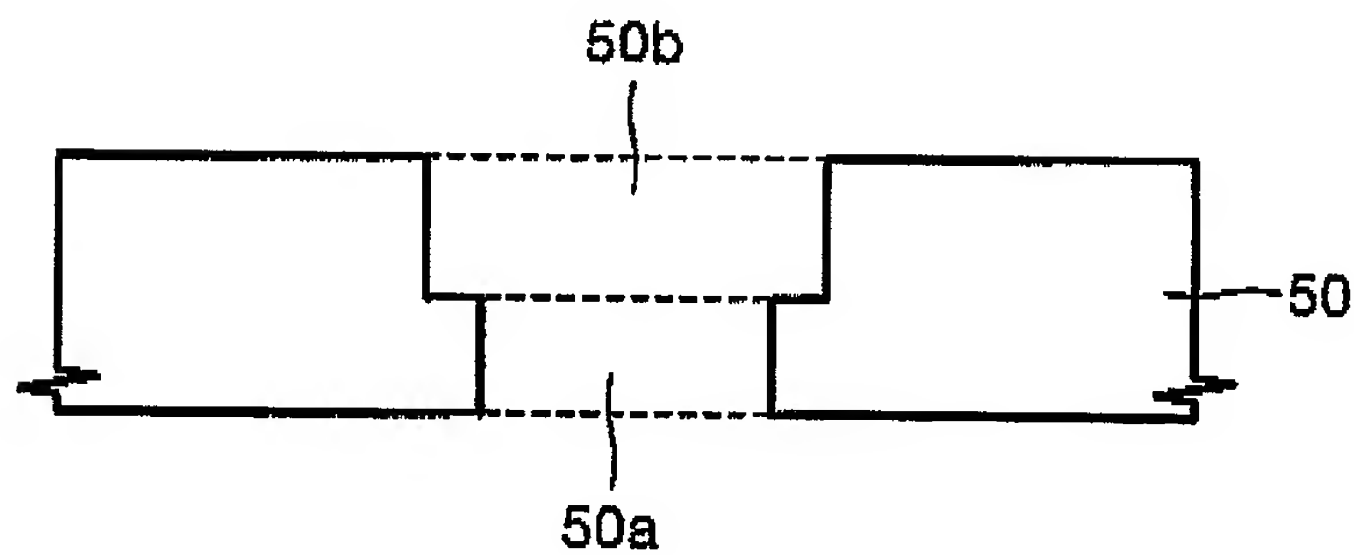
FIG. 8



Serial No Not Assigned Docket No 1751-300  
Title Method of Through-Etching Substrate  
Inventor Kyoung-dong Min, et al.

**FIG. 9****FIG. 10****FIG. 11**

Serial No. Not Assigned Docket No 1751-300  
Title Method of Through-Etching Substrate  
Inventor Kyoung-doug Min, et al.

**FIG. 12****FIG. 13**

Serial No Not Assigned Docket No 1751-300  
Title Method of Through-Etching Substrate  
Inventor Kyoung-doug Min, et al.

FIG. 14

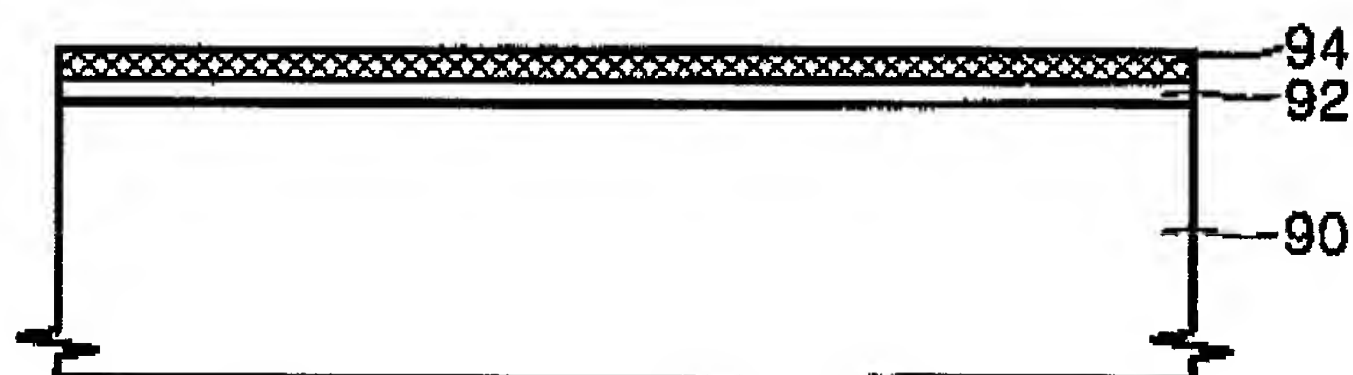
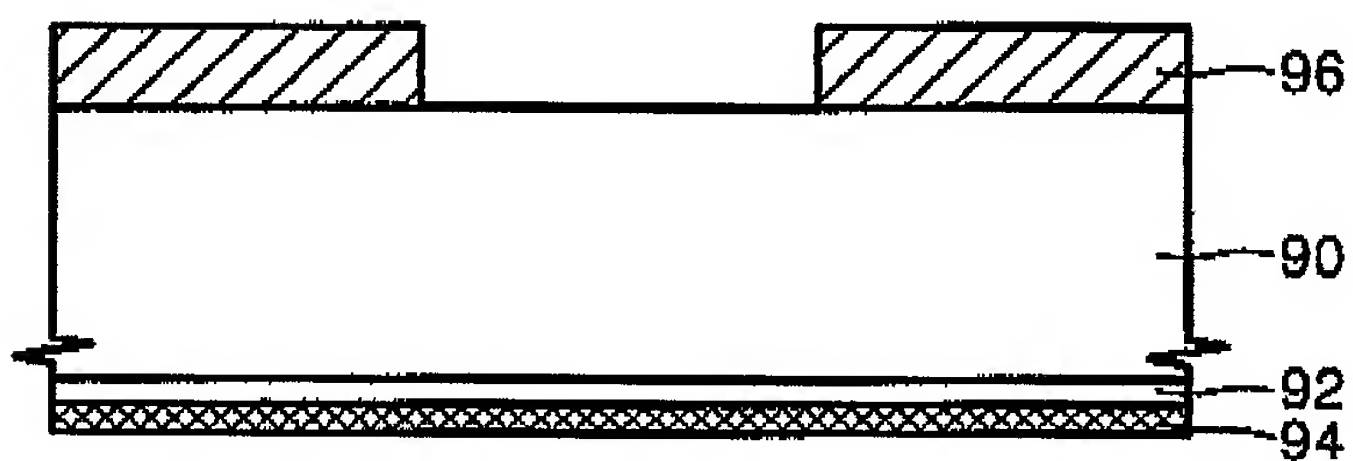
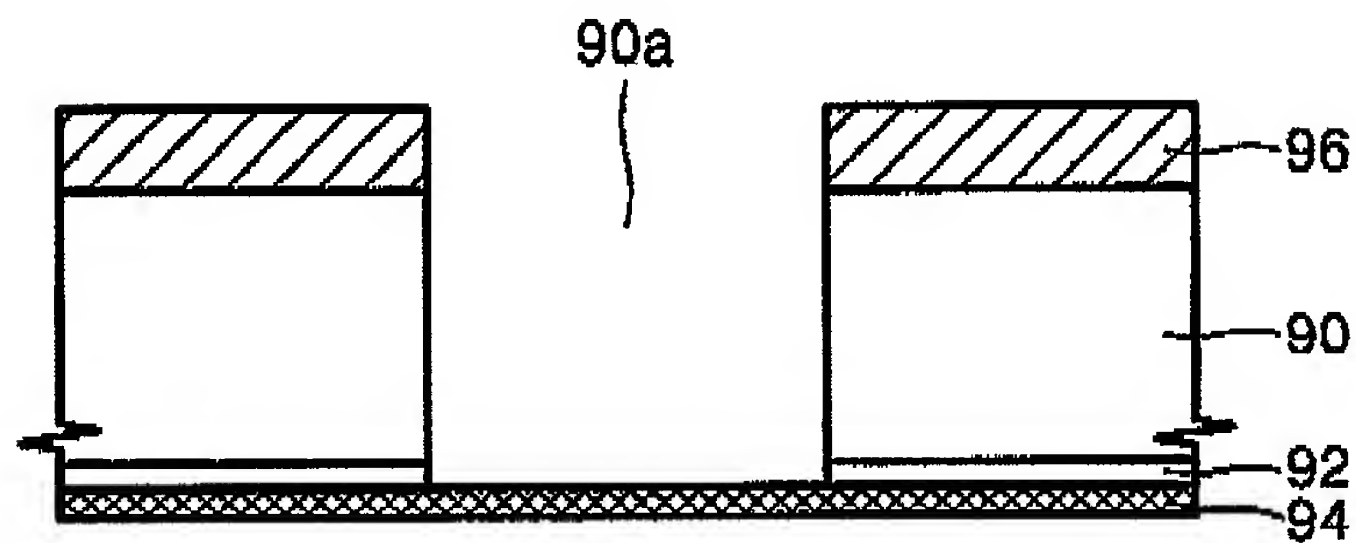


FIG. 15



Serial No. Not Assigned Docket No. 1751-300  
Title Method of Through-Etching Substrate  
Inventor Kyoung-doug Min, et al.

**FIG. 16****FIG. 17**